US Patent & Trademark Office
Patent Public Search | Text View

United States Patent Application Publication 20250262716
Kind Code A1
Publication Date August 21, 2025
Inventor(s) Vogel; David et al.

SYSTEMS AND METHODS FOR CONDITIONING BLADES

Abstract

Systems and methods for conditioning blades are provided. A method may include, for example, obtaining a cutting device, measuring various characteristics of the cutting edge of the cutting device, creating a current edge profile based on the characteristics, creating a modified edge profile, and/or conditioning the blade. Conditioning may include grinding, buffing and/or polishing. One or more of the conditioning steps may be based on the modified edge profile.

Inventors: **Vogel; David (Columbus, IN), Newell; Walker (Elizabethtown, IN)**

Applicant: **Wolff Industries, Inc.** (Spartanburg, SC)

Family ID: **1000008586927**

Appl. No.: **19/201169**

Filed: **May 07, 2025**

Related U.S. Application Data

parent US continuation 16849257 20200415 parent-grant-document US 12325105 child US 19201169
parent US continuation 15868441 20180111 parent-grant-document US 10654148 child US 16849257
parent US continuation 15272759 20160922 parent-grant-document US 9902039 child US 15868441
us-provisional-application US 62222864 20150924

Publication Classification

Int. Cl.: **B24B51/00** (20060101); **B24B3/52** (20060101); **B24B3/54** (20060101); **B24B19/00** (20060101); **B24B49/12** (20060101)

U.S. Cl.:

CPC **B24B51/00** (20130101); **B24B3/52** (20130101); **B24B3/54** (20130101); **B24B19/002** (20130101); **B24B49/12** (20130101);

Background/Summary

PRIORITY STATEMENT

[0001] The present application claims priority to U.S. Provisional Patent Application Ser. No. 62/222,864, filed Sep. 24, 2015 and which is incorporated by reference herein in its entirety.

FIELD OF THE INVENTION

[0002] The present disclosure relates generally to systems and methods for conditioning blades.

BACKGROUND OF THE INVENTION

[0003] Knives, scissors and other cutting tools are utilized on an everyday basis in a wide variety of situations, ranging from food preparation to various outdoor uses, such as chopping wood, to self-defense. In order to facilitate efficient and effective cutting by the blades of such cutting tools, and to facilitate the safety of users of the blades, the blades should be maintained with sharp, straight cutting edges. Any cutting processes result in the cutting edges of the blades quickly becoming dull and including defects, such as nicks, which necessitates periodic conditioning of the blades.

[0004] Many tools are available for conditioning blades. For example, many typically known hand-held conditioning devices utilize stationary rods which are positioned to form a blade conditioning zone therebetween at an intersection of the rods. The blade is dragged through the blade conditioning zone and contacts the rods, and this contact between the blade and the rods conditions the blade. However, such stationary rods in many cases do not adequately condition blades, and may not be suitably adaptable to a variety of blades having different sizes and shapes.

[0005] Known automated processes for conditioning blades also have various disadvantages. For example, U.S. Pat. No. 8,758,084 to Knecht et al., issued on Jun. 24, 2014 and which is incorporated by reference herein in its entirety, is directed to apparatus for grinding hand knives. U.S. Pat. No. 8,915,766 to Kolchin, issued on Dec. 23, 2014 and which is incorporated by reference herein in its entirety, is directed to automatic knife sharpeners and methods for their use. However, neither Knecht et al. nor Kolchin measures the entire edge profile of a blade to be conditioned and conditions the blade to a modified edge profile that approximates characteristics of the original edge profile, such as the curvature, etc.

[0006] Accordingly, improved systems and methods for conditioning blades are desired. In particular, automated systems and methods which measure the entire edge profile of a blade to be conditioned and condition the blade to a modified edge profile that approximates characteristics of the original edge profile would be advantageous.

BRIEF DESCRIPTION OF THE INVENTION

[0007] Aspects and advantages of the invention will be set forth in part in the following description, or may be obvious from the description, or may be learned through practice of the invention.

[0008] Systems and methods for conditioning a blade are disclosed. In exemplary embodiments, such systems and methods advantageously measure the entire edge profile of a blade to be conditioned and condition the blade to a modified edge profile that approximates characteristics of the original edge profile. The overall quality and appearance of the resulting blade and cutting edge thereof may thus be increased relative to various known blade conditioning systems and methods.

[0009] A system in accordance with the present disclosure may include, for example, a gripper assembly that grips a cutting device and moves the cutting device within the system. In particular, the gripper assembly may orient the cutting device as required for measurement of the cutting edge thereof, and may then move the cutting device such that the cutting edge contacts a grinding assembly in accordance with a modified edge profile created based on the measurements of the cutting edge. The gripper assembly may further move the cutting device such that the cutting edge contacts a buffing assembly and a polishing assembly, in some embodiments in accordance with the modified edge profile. The blade may be conditioned by grinding and, optionally, buffing and/or polishing of the cutting edge.

[0010] The system may further include a first measurement device which measures various characteristics of the blade, including for example the thickness of the blade along a width thereof. The system may further include a second measurement device which measures various characteristics of the blade, including for example, the width of the blade along a length thereof. These measurements may be utilized to create a current edge profile. A modified edge profile may then be created, based on the current edge profile.

[0011] The system may further include a grinding assembly and, optionally, a buffing assembly and/or polishing assembly. The blade may contact these assemblies for respective grinding, buffing and/or polishing purposes.

[0012] The system may further include a processor, which may be in communication with the various other components of the system as discussed herein. The processor may cause movement of the gripper assembly to initially pick up a cutting device for conditioning, and to provide the cutting device for measurement thereof. The processor may further, for example, create the current edge profile based on the measurements, and then create the modified edge profile based on the current edge profile. The processor may further cause movement of the gripper assembly, and thus the blade, in accordance with the modified edge profile and other suitable data points, directions, etc., to interact with the grinding assembly, buffing assembly and/or polishing assembly.

[0013] In one embodiment, a system for conditioning blades is provided. The system defines an orthogonal coordinate system comprising an X-axis, a Y-axis and a Z-axis. The system includes a gripper assembly for gripping a cutting device comprising a blade, the gripper assembly movable along and about the X-axis, the Y-axis and the Z-axis. The system further includes a first measuring device operable to measure a width and a thickness of the blade, wherein the gripper assembly orients the blade for measurement by the first measuring device. The system further includes a second measuring device operable to measure the width and a length of the blade, wherein the gripper assembly orients the blade for measurement by the second measuring device. The system further includes a processor, the processor configured for creating a current edge profile based on the width, thickness and length measurements, and adjusting the current edge profile to a modified edge profile.

[0014] A method in accordance with the present disclosure may include, for example, obtaining a cutting device, measuring various characteristics of the cutting edge of the cutting device, creating a current edge profile based on the characteristics, creating a modified edge profile, and/or conditioning the blade. Conditioning may include grinding, buffing and/or polishing. One or more of the conditioning steps may be based on the modified edge profile.

[0015] In one embodiment, a method for conditioning blades is provided. The method includes measuring a width, thickness and length of the blade. The method further includes creating, using a processor, a current edge profile for the entire blade based on the width, thickness and length measurements. The current edge profile includes X-axis, Y-axis and Z-axis data points for the blade. The method further includes adjusting, using a processor, the current edge profile to a modified edge profile. The method further includes conditioning the blade based on the modified edge profile.

[0016] Notably, in exemplary embodiments, systems and methods in accordance with the present disclosure may by automated. Further, conditioning may advantageously occur to the entire cutting edge of a blade being conditioned as discussed herein.

[0017] These and other features, aspects and advantages of the present invention will become better understood with reference to the following description and appended claims. The accompanying drawings, which are incorporated in and constitute a part of this specification, illustrate embodiments of the invention and, together with the description, serve to explain the principles of the invention.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

[0018] A full and enabling disclosure of the present invention, including the best mode thereof, directed to one of ordinary skill in the art, is set forth in the specification, which makes reference to the appended figures, in which:

[0019] FIG. **1** is a perspective view of a system for conditioning a blade in accordance with one embodiment of the present disclosure;

[0020] FIG. **2** is a perspective view of a gripper assembly providing a cutting device for measurement by a first measuring device in accordance with one embodiment of the present disclosure;

[0021] FIG. **3** is a side view of components of a first measuring device during measurement of a blade in accordance with one embodiment of the present disclosure;

[0022] FIG. **4** is a perspective view of a gripper assembly providing a cutting device for measurement by a second measuring device in accordance with one embodiment of the present disclosure;

[0023] FIG. **5** is a top view of components of a second measuring device during measurement of a blade in accordance with one embodiment of the present disclosure;

[0024] FIG. **6** is a perspective view of a gripper assembly providing a cutting device for grinding by a grinding assembly in accordance with one embodiment of the present disclosure;

[0025] FIG. **7** is a side view of a gripper assembly providing a cutting device for grinding by a grinding assembly in accordance with one embodiment of the present disclosure;

[0026] FIG. **8** is another side view of a gripper assembly providing a cutting device for grinding by a grinding assembly in accordance with one embodiment of the present disclosure;

[0027] FIG. **9** is a perspective view of a gripper assembly providing a cutting device for buffing by a buffing assembly in accordance with one embodiment of the present disclosure; and

[0028] FIG. **10** is a perspective view of a gripper assembly providing a cutting device for polishing by a polishing assembly in accordance with one embodiment of the present disclosure.

DETAILED DESCRIPTION OF THE INVENTION

[0029] Reference now will be made in detail to embodiments of the invention, one or more examples of which are illustrated in the drawings. Each example is provided by way of explanation of the invention, not limitation of the invention. In fact, it will be apparent to those skilled in the art that various modifications and variations can be made in the present invention without departing from the scope or spirit of the invention. For instance, features illustrated or described as part of one embodiment can be used with another embodiment to yield a still further embodiment. Thus, it is intended that the present invention covers such modifications and variations as come within the scope of the appended claims and their equivalents.

[0030] Referring now to FIG. **1**, one embodiment of a system **10** for conditioning blades in accordance with the present disclosure is provided. Systems **10** in accordance with the present disclosure advantageously facilitate efficient and accurate blade conditioning which results in conditioned blades that have edge profiles which approximate the original edge profiles of the blades. Such advantages result, for example, from accurate and efficient measurement of the current blade profile, and conditioning based on such profile. Such advantages further result, for example, from conditioning of the entire edge of the blade based on the current blade profile to obtain a conditioned blade profile which approximates the original edge profile of the blade while advantageously removing defects, such as nicks, from the edge and thinning the blade if necessary.

[0031] A coordinate system may generally be defined for the system **10**. The coordinate system may include an X-axis **12**, a Y-axis **14** and a Z-axis **16**, each of which may be mutually orthogonal to the others. Roll, pitch and yaw directions **13**, **15**, **17** are additionally defined about the X-axis **12**, Y-axis **14** and Z-axis **16**, respectively.

[0032] Referring briefly to FIGS. **3** and **5**, a blade **102** in accordance with one embodiment of the present disclosure is illustrated. The blade **102** in this embodiment is a component of a cutting device **100** (in this embodiment a knife) which includes the blade **102** and a handle **104**. The blade **102** generally extends from the handle **104**. Alternatively, the blade **102** may be a component of any other suitable cutting device **100**, such as scissors, a razor, chisel, axe, hatchet, or any cutting apparatus known in the art. In further alternative embodiments, cutting device **100** may include only the blade **102** itself, with no additional components such as handles, etc. Further, it should be understood that a blade **102** of the present disclosure may be a straight-edged blade, serrated-edge blade, or a blade with any other edge design known in the art. A conditioning system **10** of the present disclosure may interact with the blade **102** to condition the blade, such as, for example, by straightening and/or sharpening the blade.

[0033] The blade **102** may have a width **110**, a length **112**, and a thickness **114**, as illustrated and as generally understood. One or more cutting edges **106** may be defined about the perimeter of the blade **102**. For example, a blade **102** may be a single edge blade, and thus include one cutting edge **106** and an opposite spine **108**, as illustrated, or may include two opposite cutting edges **106**. The thickness **114** of the blade **102** may generally taper along a portion of the the width **110** towards the perimeter of the blade **102** to define a cutting edge **106**. It should be noted that a cutting edge **106** as utilized in accordance with the present disclosure refers to a portion of the perimeter of the blade **102** which is considered generally capable of performing a cutting task, as is generally understood. Accordingly, other portions of the perimeter which, for example, are not tapered are not considered to be portions of a cutting edge **106** as utilized herein.

[0034] Referring again to FIG. **1**, system **10** may include a processor **20**. In general, as used herein, the term “processor” refers not only to integrated circuits referred to in the art as being included in a computer, but also refers to a controller, a microcontroller, a microcomputer, a programmable logic controller (PLC), an application specific integrated circuit, and other programmable circuits. Processor **20** may also include various input/output channels for receiving inputs from and sending control signals to various other components with which the processor is in communication, such as other components of the system **10** as discussed herein. Processor **20** may generally perform various steps as discussed herein. Further, it should be understood that a processor **20** in accordance with the present disclosure may be a single master processor **20** in communication with the other various components of system **10**, and/or may include a plurality of individual component processors.

[0035] It should additionally be noted that the processor **20** or components thereof may be onboard the system **10** hardware or may be off-board, such as at a remote location. For example, in some embodiments, processor **20** or components thereof may be embodied as a remote central server that receives information from numerous in-field systems. Processor **20** or components thereof may thus be in communication with the other various components of system **10** via suitable wired and/or wireless communication.

[0036] System **10** may further include, for example, a gripper assembly **25** which may be configured to grip a cutting device **100**. The gripper assembly **25** may include one or more clamp arms **27**, as illustrated, which may contact and grip the cutting device **100** for movement and manipulation as discussed herein. For example, as illustrated the clamp arms **27** may grip a handle **104** of the cutting device **100**, advantageously leaving the blade **102** exposed for conditioning.

Jaws **29** of each clamp arm **27** may move towards each other to contact and grip a cutting device **100**, and may move away from each other to release the cutting device **100**.
[0037] The clamp arms **27** may be movable along and/or about one or more axes. For example, in exemplary embodiments, the clamp arms **27** may be movable along the X-axis **12**, Y-axis **14** and/or Z-axis **16**, and may further be rotatable in the roll direction **13**, pitch direction **15** and yaw direction **17**. Such movement of the clamp arms **27** may generally facilitate movement of the blade **102** as required for conditioning, as discussed herein.
[0038] One or more cutting devices **100** may be provided for conditioning in system **10** in a blade magazine **120**. The magazine **120** may include a plurality of slots **122** for accommodating the blades **102** of a plurality of cutting devices **100** which are provided for conditioning. The clamp arms **27** may remove a cutting device **100** from a blade magazine **120**, such as from a slot **122** therein. The blade **102** of the cutting device **100** may be conditioned in system **100**. The clamp arms **27** may then replace the cutting device **100** in either the same blade magazine **120** or a different blade magazine **120** (and slot **122** thereof) when conditioning is finished.
[0039] Referring now to FIGS. **2** and **3**, system **10** may further include a first measuring device **30**. The first measuring device **30** may generally be configured to measure a width **110** and thickness **114** of the blade **102**, and to output data points corresponding to the thickness **114** along the width **110** at one or more locations along the length **112** of the blade **102**.
[0040] For example, device **30** may include a first laser **32** and a second laser **34** which may each be configured to emit laser light beams **33**, **35**. The lasers **32**, **34** may, for example, be spaced apart from each other along the Z-axis **16** and may face each other. Light beams **33**, **35** may be emitted along or at an angle to the Z-axis **16** generally towards each other, and may intersect at a focal point **36** between the lasers **32**, **34** when there are no obstructions between the lasers **32**, **34**. The blade **102** may be moved (by the gripper assembly **25**) into a position such that the width **110** of the blade **102** is approximately within an X-axis **12**/Y-axis **14** plane and aligned along the X-axis **12**. Accordingly, the width **110** may extend along the X-axis **12**, the length **112** may extend along the Y-axis **14**, and the thickness **114** may extend along the Z-axis **16**. The blade **102** may then be moved across the focal point **36**, such as in a direction along the X-axis **12**. The blade **102** may break the interaction of the laser light beams **33**, **35**, and such contact by the laser light beams **33**, **35** with the blade **102** may cause measurement of the blade **102**. For example, the blade **102** may move along the X-axis **12**. The width **110** at a location along the length **112** may be measured based on when and where during such movement that beams **33**, **35** initially contact the blade **102** and subsequently cease contact with the blade **102**. Additionally, the thickness **114** throughout such width **110** can be measured, based on the distance travelled by the beams **33**, **35** before they contact the blade **102**. In some embodiments, such measurement may be taken only once at a particular location along the Y-axis **14** for the blade **102**. Accordingly, no movement of the blade **102** along the Y-axis **14** may be required. Alternatively, multiple measurements may be taken at various locations along the Y-axis **14** (and thus along the length **112** of the blade **102**), with movement of the blade **102** along the Y-axis **14** occurring between such movements along the X-axis **12**.
[0041] Data points for the dimensions measured by the first measuring device **30** may stored, such as in processor **20**. The data points may include thickness **114** data points (along the Z-axis **16**) and width **110** data points (along the X-axis **12**), as well as length **112** data points (along the Y-axis **14**). The data points may be utilized in a profile of the blade **102**, as discussed herein.
[0042] Referring now to FIGS. **4** and **5**, system **10** may further include a second measuring device **40**. The second measuring device **40** may generally be configured to measure a width **110** and length **112** of the blade **102**, and to output data points corresponding to the width **110** along the length **112** of the blade **102**.
[0043] Second measuring device **40** may, for example, include an imaging device **42** and a light source **44**. The imaging device **42** and light source **44** may, for example, be spaced apart from each other along the Z-axis **16** and may face each other. Light **45** may be emitted along or at an angle to

the Z-axis **16** generally towards the imaging device **42**. Imaging device **42** may be configured to obtain images, and may be oriented such that the images are in a X-axis **12**/Y-axis **14** plane.

[0044] Imaging device **42** may include a lens assembly **43** and an image capture device (which may be processor **20** or a component thereof). Lens assembly **43** may generally magnify images viewed by the lens assembly **43** for processing by the image capture device. Lens assembly **43** in some embodiments may, for example, be a suitable camera lens, telescope lens, etc., and may include one or more lens spaced apart to provide the required magnification. The image capture device may generally be in communication with the lens assembly **43** for receiving and processing light from the lens assembly **43** to generate images. In exemplary embodiments, for example, the image capture device may be a camera sensor which receives and processes light from a camera lens to generate images, such as digital images, as is generally understood.

[0045] Imaging device **42** may be utilized to obtain images of the blade **102**, such as of the width **110** and length **112** thereof. For example, the blade **102** may be moved (by the gripper assembly **25**) into a position such that the width **110** of the blade **102** is approximately within an X-axis **12**/Y-axis **14** plane and aligned along the X-axis **12**. Accordingly, the width **110** may extend along the X-axis **12**, the length **112** may extend along the Y-axis **14**, and the thickness **114** may extend along the Z-axis **16**. The blade **102** may then be moved such that a portion of the blade **102** is within an imaging zone, i.e. is visible to the imaging device **42** (such as through the lens assembly **43** thereof). In exemplary embodiments, and utilizing data points from the first blade measurement using the first measuring device **30**, the blade **102** may be positioned such that the cutting edge **106** at a length-wise location measured during the first blade measurement is centered within the imaging zone along the X-axis **12** and, optionally, the Y-axis **14**. The light source **44** may be activated, such that light **45** emitted towards the imaging device **42**. The light **45** may backlight the blade **102**, and provide contrast between the blade **102** (and cutting edge **106** thereof) and the background in the imaging zone. The imaging device **42** may then obtain an image of the portion of the blade **102** within the imaging zone.

[0046] Once an image is obtained, the blade **102** may be moved, such as along the Y-axis **14**, such that another portion of the blade **102** is within the imaging zone. In exemplary embodiments, the cutting edge **106** at a length-wise location may be centered within the imaging zone along the X-axis **12** and, optionally, the Y-axis **14**. The light source **44** may be activated (or may remain activated), and a subsequent image of the portion of the blade **102** may be obtained. The blade **102** may be further moved, such as along the Y-axis **14**, and images obtained in a similar manner until the entire cutting edge of the blade **102** (and in some embodiments the entire blade **102**) has been imaged.

[0047] Data points, such as X-axis **12** and Y-axis data points, may be obtained based on the images. In particular, X-axis **12** and Y-axis data points may be obtained for the cutting edge **106**. These data points may be based on analysis of the pixels of the images, and in particular on the transition between different color or gray-scale ranges in the pixels which denote a transition from background to blade **102** surface.

[0048] The data points generated during the first and second measurements (such as by the first measuring device **30** and the second measuring device **40**) may be utilized to create a current edge profile for the blade **102**. The current edge profile may include X-axis **12** data points, Y-axis **14** data points, and yaw angle **17** data points which locate the blade **102**, and cutting edge **106** thereof, in space. The current edge profile may further include, for example, Z-axis **16** data points, roll angle **13** data points, and/or pitch angle **15** data points. These data points may be generated based on the data points measured during the first and second measurements (such as by the first measuring device **30** and the second measuring device **40**).

[0049] It should be noted that the first and second measurements may occur a single time or multiple times for evaluation of a blade. In exemplary embodiments, alternating first and second measurements may be performed. For example, in some embodiments, an additional first measurement may occur after the second measurement. An additional second measurement may, in some embodiments, occur after the additional first measurement.

[0050] As discussed, the first and second measurements may in exemplary embodiments occur for the entire blade **102**. Further, such measurements may be performed at a relatively fast rate. For example, data points during the first and/or second measurement may be generated in some embodiments at a rate of greater than or equal to 1 data point per 0.0001 seconds, such as greater than or equal to 1 data point per 0.00009 seconds, such as one data point per 0.000085 seconds. In some embodiments, greater than or equal to 16,000 data points can be collected along an axis in less than or equal to 2 seconds for a six-inch long blade.

[0051] As discussed, the cutting edge **106** may include various defects, such as nicks, etc. Further, the thickness **114** of the blade **102** at or adjacent to the cutting edge **106**, in some cases, may be greater than desired. Such defects and increased thickness may be caused by use of the blade **102**, and are considered undesirable. To facilitate removal of edge defects, the current edge profile obtained as discussed herein may be modified to obtain a modified edge profile. For example, data points, such as X-axis data points, wherein defects are present may be deleted from the current edge profile. Defects may be detected as significant differences between a subject data point and the neighboring data points. For example, a difference between a subject data point and one or both neighboring data points may be compared to a predetermined threshold difference. When the difference is above such threshold, the subject data point may be considered correspond to a defect. Substitute data points, such as substitute X-axis data points, may be added to the profile to replace the original data points. These data points may be obtained by, for example, calculating suitable substitute data points based on neighboring data points (above and below the subject data point along the Y-axis and at Y-axis locations wherein there are no detected defects). For example, if only one substitute data point is needed, the neighboring data points may be averaged to obtain the substitute data point. If more than one data point is needed, the substitute data points may be calculated linearly between the neighboring data points.

[0052] Once substitute data points have been provided at all defect locations (such at all necessary X-axis data points), the X-axis data points for the profile may collectively be adjusted by a predetermined amount. In exemplary embodiments, a predetermined amount (corresponding to a desired amount of material to be removed during grinding of the blade **102**) may be subtracted from each X-axis data point. The predetermined amount may be the same for each X-axis data point. Notably, in some embodiments, the predetermined amount may be based on the defects, such as the X-axis data points for the defects. For example, the predetermined amount may be equal to or greater than the size of the largest defect (in the X-axis direction). The resulting data set, including the adjusted X-axis data points, may form a modified edge profile which may be utilized for conditioning purposes. In some embodiments, the X-axis data points may additionally be smoothed either before or after such adjustment. Suitable non-parametric regression methods may, for example, be utilized to perform such smoothing.

[0053] To facilitate thinning of the blade, the thickness **114** of the blade **102** along the width **110** may be compared to a predetermined maximum thickness. If the thickness **114** is above the predetermined maximum, it may be determined that thinning is required.

[0054] Notably, the various analyses performed herein, such as by processor **20**, may be performed on a significantly large number of data points. Additionally, a significantly large number of calculations may be performed. Analysis of such magnitude advantageously provides improved resulting blade quality. In some embodiments, for example, greater than or equal to 16,000 data points may be collected and greater than 1.8 billion calculations performed for each axis for a 6-inch blade.

[0055] Referring now to FIGS. **6** through **8**, system **10** may further include a grinding assembly **50**. Grinding assembly **50** may include one or more wheels **52** or other movable devices on which an abrasive grinding media **54** may be provided. The grinding media **54** be moved, such as rotated, and blade **102** may be brought into contact with grinding media **54** to remove material from the blade **102**. In the embodiment illustrated, the grinding media **54** forms a belt which is provided on one or more wheels **52** (only one of which is shown) and driven thereby. Grinding assembly **50** may generally be utilized for grinding of the blade **102**. In particular, the blade **102** may be moved into contact with grinding media **54**, and moved in a pattern while in contact with grinding media **54**, such that the cutting edge **106** is ground to match the modified edge profile. Gripper assembly **25** may generally move the blade **102**, based on the modified edge profile to contact the grinding media **54** in such manner. Notably, in exemplary embodiments, the entire cutting edge **106** is conditioned by the grinding assembly **50**. In other words, the grinding assembly may contact the entire cutting edge **106** during grinding of the blade **102**.

[0056] To facilitate grinding, the blade **102** may be moved along the X-axis **12** and Y-axis **14** and rotated in the yaw direction **17**, and may further be moved along the Z-axis **16**, rotated in the roll direction **13** and/or rotated in the pitch direction **15**, based on the modified edge profile and data points thereof. The movements may advantageously facilitate grinding of the cutting edge **106** to the modified edge profile. Gripper assembly **25** may, for example, move the blade **102** according to the modified edge profile.

[0057] Additionally, blade **102** may be moved into contact with the grinding assembly **50** to thin the blade **102** if required, as discussed herein. Such thinning may, in exemplary embodiments, occur before grinding based on the modified edge profile. Movement of the blade **102** for thinning purposes may be based on a difference between the measured thickness of the blade **102** and the predetermined maximum thickness, as discussed above, such that the blade **102** is ground to at or below the predetermined maximum thickness. Gripper assembly **25** may, for example, move the blade **102** according to the required thickness reduction requirement.

[0058] Notably, as illustrated in FIGS. **6** through **8**, opposing sides of the blade **102** may be brought into contact with the grinding assembly **50** during grinding to thin the blade **102** and/or during grinding according to the modified edge profile. FIGS. **6** and **7** illustrate grinding on one side of the blade **102**, and FIG. **8** illustrates grinding on the opposing side of the blade **102**. When grinding to thin the blade, the thickness of the blade may be reduced through grinding on both sides of the blade **102**, with approximately equal thickness removal from each side occurring. When grinding according to the modified edge profile, the modified edge profile may be utilized for grinding on both sides, and in exemplary embodiments the entire cutting edge **106** may be conditioned during grinding on both sides.

[0059] In some embodiments, after grinding of the blade **102** to the modified edge profile, the blade **102** may be returned to the first measuring device **30** and/or second measuring device **40**. The device(s) **30**, **40** may measure the blade **102** as discussed above to inspect the blade **102**. For example, an inspection edge profile created by such subsequent measurements and resulting data points may be compared to the modified edge profile. Additionally or alternatively, any remaining defects and/or thickness issues may be identified. If such issues remain, a subsequent modified edge profile may be created and the cutting device **100** again provided for grinding, as discussed above.

[0060] Referring now to FIG. **9**, system **10** may further include a buffing assembly **60**. The buffing assembly **60** may be configured for buffing the blade **102**, such as the cutting edge **102** thereof, to for example deburr the cutting edge **102**. Buffing assembly **60** may include, for example, one or more wheels **62** or other movable devices on which abrasive buffing media **64** are provided. Notably, abrasive buffing media **64** may be finer than abrasive grinding media **54**. In exemplary embodiments, two wheels **62**, on each of which is provided an abrasive buffing media **64**, are provided. The cutting edge **102** may be moved to between the wheels **62**, such that abrasive buffing media **64** contacts both sides of the blade **100** and the cutting edge **102**. Movement of the abrasive buffing media **64** (such as rotation on the wheels **62**) may buff the cutting edge **102** to remove burrs therefrom. In exemplary embodiments, the entire cutting edge **102** may be buffed. Gripper assembly **25** may, for example, move the blade **102** into contact with the buffing assembly **60** as required, and may do so based for example on the modified edge profile or the inspection edge profile.

[0061] Referring now to FIG. **10**, system **10** may further include a polishing assembly **70**. The polishing assembly **70** may be configured for polishing the blade **102**, such as the cutting edge **102** thereof. Such polishing may, for example, occur after buffing. Polishing assembly **70** may include, for example, one or more wheels **72** or other movable devices on which abrasive polishing media **74** are provided. Notably, abrasive polishing media **74** may be finer than abrasive buffing media **64**. In exemplary embodiments, two wheels **72**, on each of which is provided an abrasive polishing media **74**, are provided. The cutting edge **102** may be moved to between the wheels **72**, such that abrasive polishing media **74** contacts both sides of the blade **100** and the cutting edge **102**. Movement of the abrasive polishing media **74** (such as rotation on the wheels **72**) may polish the cutting edge **102**. In exemplary embodiments, the entire cutting edge **102** may be polished. Gripper assembly **25** may, for example, move the blade **102** into contact with the polishing assembly **70** as required, and may do so based for example on the modified edge profile or the inspection edge profile.

[0062] Notably, processor **20** may be in communication with gripper assembly **25**, first measuring device **30**, second measuring device **40**, grinding assembly **50**, buffing assembly **60** and/or polishing assembly **70**. For example, processor **20** may activate and deactivate the measuring device **30**, second measuring device **40**, grinding assembly **50**, buffing assembly **60** and/or polishing assembly **70** as required. Further, the processor **20** may activate the gripper assembly **25** to move as discussed herein, to facilitate movement of cutting devices **100** for conditioning purposes as discussed herein.

[0063] System **10** may further include various features for monitoring performance of the system **10** during operation thereof. For example, sensors, such as ultrasonic sensors, temperature sensors, and/or voltage sensors, may be provided on various components such as bearings, power supplies, etc. of the system **10**. Data from these sensors may be provided to the processor **20**, such as at predetermined intervals. Position data for the gripper assembly **25** may additionally be provided to the processor **20**, such as at predetermined intervals. Such data may advantageously allow operators of the system **10** to monitor the system, remotely and/or on-site, and address any issues with the system **10** in an efficient manner.

[0064] It should further be understood that the various processes that may occur as described herein may, for example, be performed automatically. Accordingly, user inputs between the various steps (and other than to calibrate the system **10** and/or begin the process) may not be required.

[0065] This written description uses examples to disclose the invention, including the best mode, and also to enable any person skilled in the art to practice the invention, including making and using any devices or systems and performing any incorporated methods. The patentable scope of the invention is defined by the claims, and may include other examples that occur to those skilled in the art. Such other examples are intended to be within the scope of the claims if they include structural elements that do not differ from the literal language of the claims, or if they include equivalent structural elements with insubstantial differences from the literal languages of the claims.

Claims

1-20. (canceled)

21. A method for conditioning blades, the method comprising: gripping a cutting device comprising a blade; orienting the blade for measurement by a first measurement device, wherein the first measuring device measures a thickness of the blade; orienting the blade for measurement by a second measurement device, wherein the second measuring device measures a width and a length of the blade; creating, using a processor, a current edge profile based on the width, thickness and length measurements, the current edge profile comprising X-axis, Y-axis and Z-axis data points for the blade; and conditioning the blade.

22. The method of claim 21, wherein orienting the blade for measurement by the first measurement device occurs before orienting the blade for measurement by the second measurement device.

23. The method of claim 21, wherein orienting the blade for measurement by the first measurement device occurs after orienting the blade for measurement by the second measurement device.

24. The method of claim 21, wherein the first measuring device further measures the width and the length of the blade.

25. The method of claim 21, further comprising adjusting, using a processor, the current edge profile to a modified edge profile, and wherein conditioning of the blade is based on the modified edge profile.

26. The method of claim 25, wherein adjusting the current edge profile to the modified edge profile comprises deleting X-axis data points which correspond to defects.

27. The method of claim 26, wherein adjusting the current edge profile to the modified edge profile further comprises adding substitute X-axis data points to replace the deleted X-axis data points.

28. The method of claim 25, wherein adjusting the current edge profile to the modified edge profile comprises comparing the thickness to a predetermined maximum thickness.

29. The method of claim 21, wherein conditioning the blade comprises grinding a cutting edge of the blade.

30. The method of claim 21, wherein conditioning the blade comprises thinning a cutting edge of the blade.

31. A method for conditioning blades, the method comprising: gripping a cutting device comprising a blade; orienting the blade for measurement by a first measurement device and a second measurement device; measuring, by the first measuring device and the second measurement device, a width, length, and thickness of the blade; determining, based on the thickness of the blade, whether thinning of the blade is required; and conditioning the blade.

32. The method of claim 31, wherein determining whether thinning of the blade is required comprises comparing the thickness to a predetermined maximum thickness.

33. The method of claim 31, further comprising creating, using a processor, a current edge profile based on the width, thickness and length measurements, the current edge profile comprising X-axis, Y-axis and Z-axis data points for the blade.

34. The method of claim 33, further comprising adjusting, using a processor, the current edge profile to a modified edge profile, and wherein conditioning of the blade is based on the modified edge profile.

35. The method of claim 31, wherein conditioning the blade comprises grinding a cutting edge of the blade.

36. The method of claim 31, wherein conditioning the blade comprises thinning a cutting edge of the blade.